

**COAXIAL VIA STRUCTURE FOR OPTIMIZING SIGNAL TRANSMISSION  
IN MULTIPLE LAYER ELECTRONIC DEVICE CARRIERS**

**ABSTRACT**

A coaxial via structure adapted to transmit high speed  
5 signals or high intensity current through conductive layers of an  
electronic device carrier is provided. The coaxial via structure  
comprises a central conductive track and an external conductive  
track separated by a dielectric material and is positioned in a  
core of the electronic device carrier or in the full thickness of  
10 the electronic device. The coaxial via structure can be combined  
with a stacked via structure so as allow efficient transmission  
of high speed signals across the electronic device carrier when a  
manufacturing process limits the creation of a full coaxial via  
structure across the entire electronic device carrier.